

2SC1345

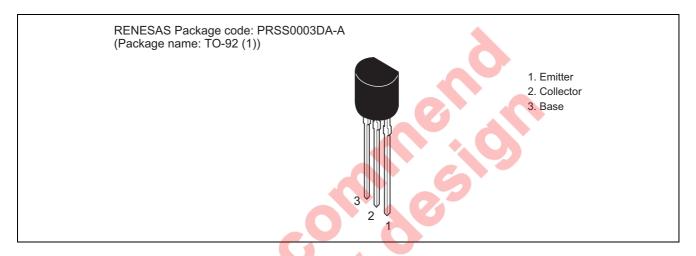
Silicon NPN Epitaxial

REJ03G0687-0300 (Previous ADE-208-1052A) Rev.3.00 Sep.10.2005

Application

Low frequency low noise amplifier

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	55	V
Collector to emitter voltage	$V_{\sf CEO}$	50	V
Emitter to base voltage	V_{EBO}	5	V
Collector current	Ic	100	mA
Collector power dissipation	Pc	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	55	_	_	V	$I_C = -10 \mu A, I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	50	_	_	V	$I_C = 1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	_	_	V	$I_E = 10 \mu A, I_C = 0$
Collector cutoff current	I _{CBO}	_	_	0.5	μΑ	$V_{CB} = 18 \text{ V}, I_{E} = 0$
Emitter cutoff current	I _{EBO}	_	_	0.5	μΑ	$V_{EB} = 2 \text{ V}, I_{C} = 0$
DC current transfer ratio	h _{FE} *1	250	_	1200		V _{CE} = 12 V, I _C = 2 mA
Base to emitter voltage	V_{BE}	_	_	0.75	V	V _{CE} = 12 V, I _C = 2 mA
Collector to emitter saturation voltage	V _{CE(sat)}	_	_	0.5	V	$I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$
Gain bandwidth product	f⊤	_	230	_	MHz	V _{CE} = 12 V, I _C = 2 mA
Collector output capacitance	Cob	_	_	3.5	pF	$V_{CB} = 10 \text{ V}, I_{E} = 0,$ f = 1 MHz
Noise figure	NF	_	_	8	dB	$V_{CE} = 6 \text{ V, } I_{C} = 0.1 \text{ mA,}$ $f = 10 \text{ Hz, } R_{g} = 10 \text{ k}\Omega$
		_	_	1	dB	$V_{CE} = 6 \text{ V}, I_{C} = 0.1 \text{ mA},$ f = 1 kHz, $R_{g} = 10 \text{ k}\Omega$

Note: 1. The 2SC1345 is grouped by h_{FE} as follows.

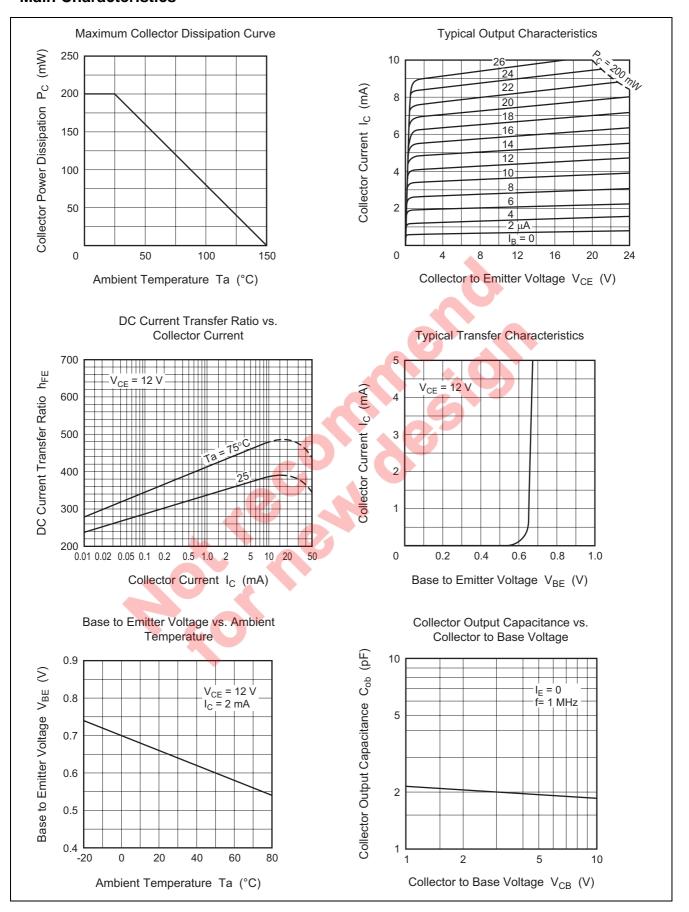
D	ш	F	
250 to 500	400 to 800	600 to 1200	

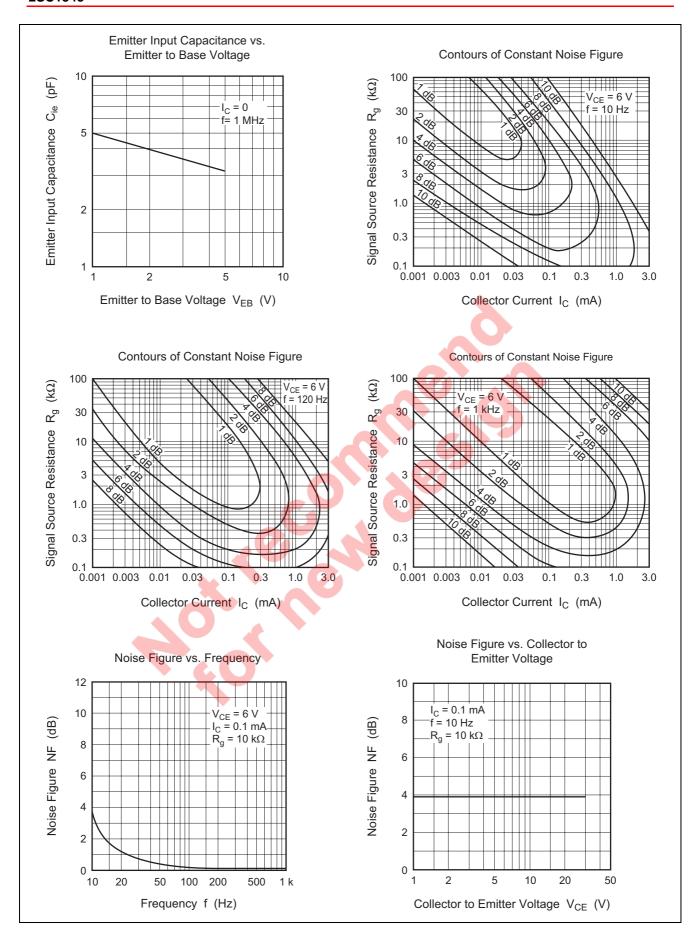
Small Signal h Parameters

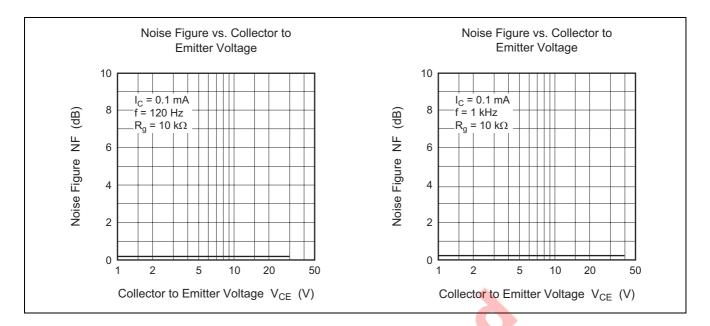
 $(V_{CE} = 5V, I_C = 0.1 \text{ mA}, f = 270 \text{ Hz}, Ta = 25^{\circ}\text{C}, \text{ Emitter common})$

		- V			
ltem	Symbol	D	E	F	Unit
Input impedance	hie	110	170	240	kΩ
Voltage feedback ratio	hre	9.5	14.5	16	× 10 ⁻⁴
Current transfer ratio	hfe	340	540	825	
Output admittance	hoe	12.0	12.5	13.5	μS

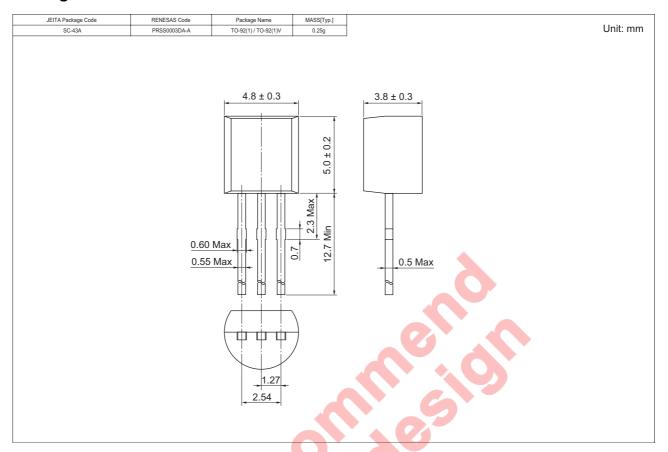
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SC1345ETZ-E	2500	Hold Box, Radial Taping
2SC1345FTZ-E		

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